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- C SUFFIX ... NT PACKAGE Second-Generation PLD Architecture M SUFFIX . . . JT OR W PACKAGE (TOP VIEW) **Choice of Operating Speeds** TIBPAL22V10AC ... 25 ns Max CLK/I 24 Vcc TIBPAL22V10AM ... 30 ns Max 1 23 1 I/O/Q ١ſ 2 TIBPAL22V10C ... 35 ns Max II 3 22 1 I/O/Q Increased Logic Power - Up to 22 Inputs 21 1 I/O/Q IΠ 4 and 10 Outputs 20 1 I/O/Q IГ 5 19 I/O/Q IΓ 6 Increased Product Terms – Average of 12 IΓ 7 18 1/O/Q Per Output 17 1/O/Q ΙГ 8 Variable Product Term Distribution 16 🛛 I/O/Q ١ſ 9 **Allows More Complex Functions to Be** 15 1 I/O/Q П 10 Implemented 14 1/0/Q П 11 GND 12 13 Each Output Is User Programmable for **Registered or Combinational Operation**, Polarity, and Output Enable Control C SUFFIX ... FN PACKAGE **M SUFFIX ... FK PACKAGE TTL-Level Preload for Improved Testability** (TOP VIEW) **Extra Terms Provide Logical Synchronous** 2000 1000 Set and Asynchronous Reset Capability 5 Fast Programming, High Programming 3 2 1 28 27 26 Yield, and Unsurpassed Reliability Ensured 5 25 1/0/Q h **Using Ti-W Fuses** 6 24 Т I/O/Q 7 23 I/O/Q 1 AC and DC Testing Done at the Factory NC I 8 22 NC **Utilizing Special Designed-In Test Features** Π9 I/O/Q 21 1 **Dependable Texas Instruments Quality and** 10 20 I/O/Q 1
- Package Options Include Both Plastic and Ceramic Chip Carriers in Addition to Plastic and Ceramic DIPs
- Functionally Equivalent to AMDs AMPAL22V10 and AMPAL22V10A

#### description

Reliability

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The TIBPAL22V10 and TIBPAL22V10A are programmable array logic devices featuring high speed and functional equivalency when compared to presently available devices. They are implemented with the familiar sum-of-products (AND-OR) logic structure featuring the new concept "Programmable Output Logic Macrocell". These IMPACT<sup>™</sup> circuits combine the latest Advanced Low-Power Schottky technology with proven titanium-tungsten fuses to provide reliable, high-performance substitutes for conventional TTL logic.

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Pin assignments in operating mode

NC - No internal connection

These devices contain up to 22 inputs and 10 outputs. They incorporate the unique capability of defining and programming the architecture of each output on an individual basis. Outputs may be registered or nonregistered and inverting or noninverting as shown in the output logic macrocell diagram. The ten potential outputs are enabled through the use of individual product terms.

These devices are covered by U.S. Patent 4,410,987. IMPACT is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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#### description (continued)

Further advantages can be seen in the introduction of variable product term distribution. This technique allocates from 8 to 16 logical product terms to each output for an average of 12 product terms per output. This variable allocation of terms allows far more complex functions to be implemented than in previously available devices.

Circuit design is enhanced by the addition of a synchronous set and an asynchronous reset product term. These functions are common to all registers. When the synchronous set product term is a logic 1, the output registers are loaded with a logic 1 on the next low-to-high clock transition. When the asynchronous reset product term is a logic 1, the output registers are loaded with a logic 0. The output logic level after set or reset depends on the polarity selected during programming. Output registers can be preloaded to any desired state during testing. Preloading permits full logical verification during product testing.

With features such as programmable output logic macrocells and variable product term distribution, the TIBPAL22V10 and TIBPAL22V10A offer quick design and development of custom LSI functions with complexities of 500 to 800 equivalent gates. Since each of the ten output pins may be individually configured as inputs on either a temporary or permanent basis, functions requiring up to 21 inputs and a single output or down to 12 inputs and 10 outputs are possible.

A power-up clear function is supplied that forces all registered outputs to a predetermined state after power is applied to the device. Registered outputs selected as active-low power up with their outputs high. Registered outputs selected as active-high power up with their outputs low.

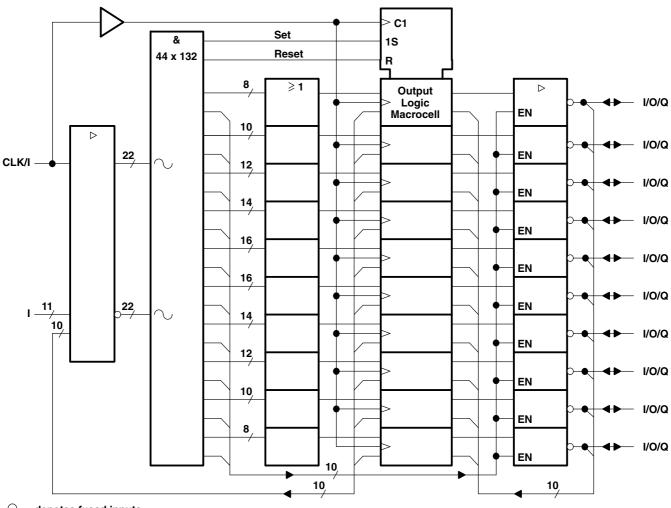
A single security fuse is provided on each device to discourage unauthorized copying of fuse patterns. Once blown, the verification circuitry is disabled and all other fuses will appear to be open.

The TIBPAL22V10C and TIBPAL22V10AC are characterized for operation from 0°C to 75°C. The TIBPAL22V10AM is characterized for operation over the full military temperature range of –55°C to125°C.



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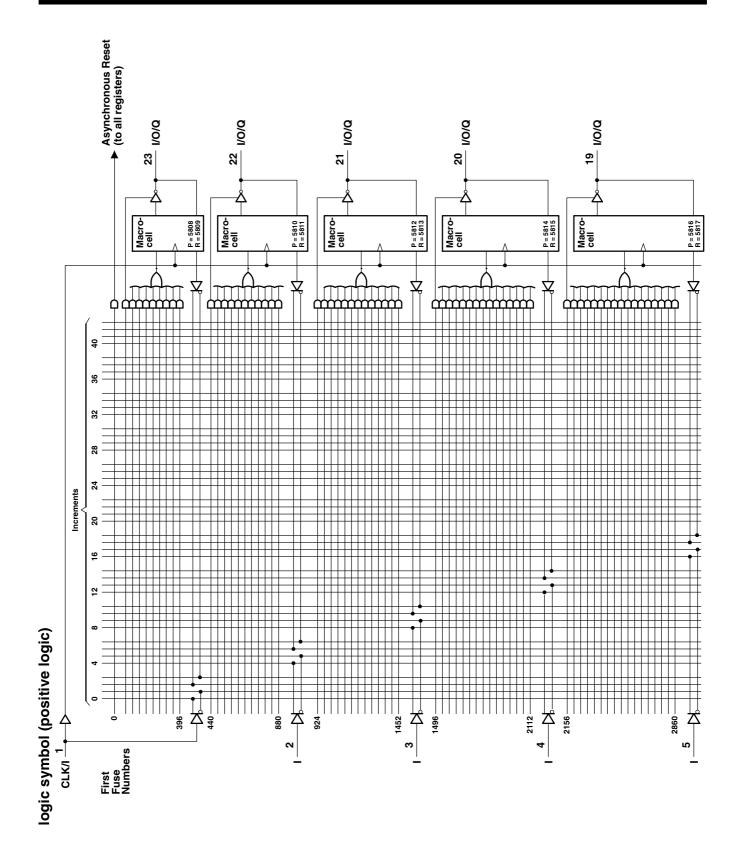
functional block diagram (positive logic)



 $\sim\,$  denotes fused inputs

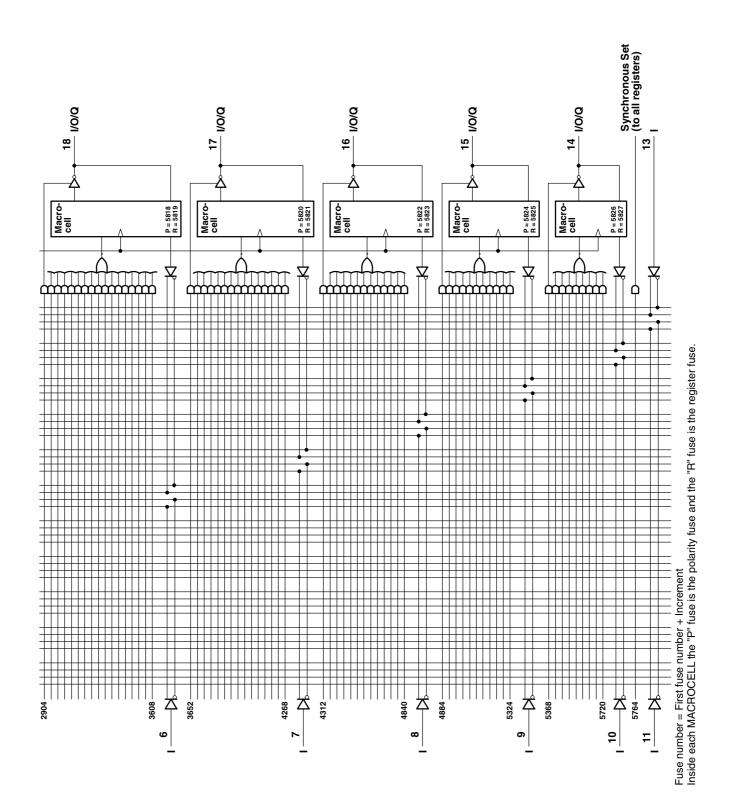


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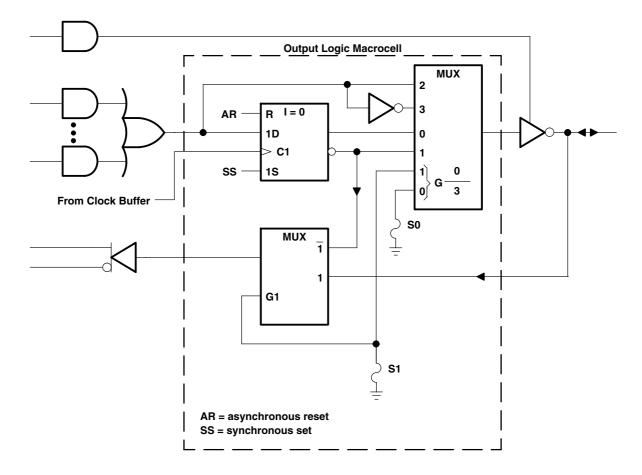
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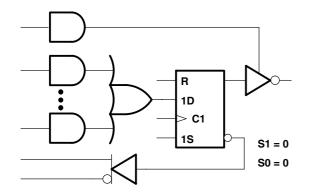
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#### output logic macrocell diagram

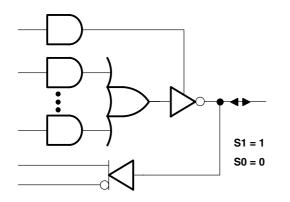




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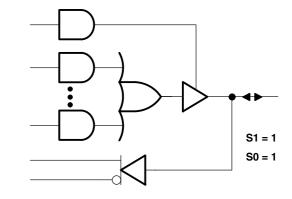


#### REGISTER FEEDBACK, REGISTERED, ACTIVE-LOW OUTPUT



R ID C1 S1 = 0 S0 = 1

#### **REGISTER FEEDBACK, REGISTERED, ACTIVE-HIGH OUTPUT**



I/O FEEDBACK, COMBINATIONAL, ACTIVE-LOW OUTPUT

#### I/O FEEDBACK, COMBINATIONAL, ACTIVE-HIGH OUTPUT

#### MACROCELL FEEDBACK AND OUTPUT FUNCTION TABLE

FUSE S	ELECT			
S1	S0	FEEDBACK AND		JURATION
0	0	Register feedback	Registered	Active low
0	1	Register feedback	Registered	Active high
1	0	I/O feedback	Combinational	Active low
1	1	I/O feedback	Combinational	Active high

0 = unblown fuse, 1 = blown fuse

S1 and S0 are select-function fuses as shown in the output logic macrocell diagram.

#### Figure 1. Resultant Macrocell Feedback and Output Logic After Programming



## TIBPAL22V10AM is Not Recommended For New Designs

# TIBPAL22V10C, TIBPAL22V10AC HIGH-PERFORMANCE IMPACT TM PROGRAMMABLE ARRAY LOGIC CIRCUITS

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage (see Note 1)	–5.5 V
Voltage range applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	0°C to 75°C
Storage temperature range	−65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

#### recommended operating conditions

			TIBPAL22V10C			TIBP				
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V <sub>CC</sub>	Supply voltage		4.75	5	5.25	4.75	5	5.25	V	
VIH	High-level input voltage	2		5.5	2		5.5	V		
VIL	Low-level input voltage			0.8			0.8	V		
I <sub>ОН</sub>	High-level output current			-3.2			-3.2	mA		
I <sub>OL</sub>	Low-level output current			16			16	mA		
f <sub>clock</sub>	Clock frequency <sup>†</sup>			18			28.5	MHz		
tw	Pulse duration	Clock high or low	25			15			ns	
۲W	Fulse duration	Asynchronous reset high or low	35			25			115	
		Input	30			20				
+	Setup time before clock↑	Feedback	30			20			ns	
t <sub>su</sub>		Synchronous set	30			25			115	
		Asynchronous reset low (inactive)	35			25				
t <sub>h</sub>	Hold time, input, set, or feed	back after clock $\uparrow$	0			0			ns	
T <sub>A</sub>	Operating free-air temperatu	re	0		75	0		75	°C	

<sup>†</sup>  $f_{clock}$  (with feedback) =  $\frac{1}{t_{su} + t_{pd}(CLK \text{ to } Q)}$ ,  $f_{clock}$  (without feedback) =  $\frac{1}{t_{W}(low) + t_{W}(high)}$ 



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#### electrical characteristics over recommended operating free-air temperature range

		_	TEST CONDITIONS					TIBP	AL22V1	0AC	
PARAMETER		1	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT		
V <sub>IK</sub>		V <sub>CC</sub> = 4.75 V,	$I_{I} = -18 \text{ mA}$				-1.2			-1.2	V
V <sub>OH</sub>		V <sub>CC</sub> = 4.75 V,	I <sub>OH</sub> = -3.2 mA		2.4	3.5		2.4	3.5		V
V <sub>OL</sub>		V <sub>CC</sub> = 4.75 V,	l <sub>OL</sub> = 16 mA			0.35	0.5		0.35	0.5	V
I <sub>OZH</sub>		V <sub>CC</sub> = 5.25 V,	V <sub>O</sub> = 2.7 V				0.1			0.1	mA
	Any output	V <sub>CC</sub> = 5.25 V,	$V_{\rm c} = 0.4 V_{\rm c}$				-100			-100	۵
IIL	Any I/O	VCC = 5.25 V,	V  = 0.4 V				-250			-250	μA
l <sub>l</sub>		$V_{CC} = 5.25 V,$	V <sub>I</sub> = 5.5 V				1			1	mA
I <sub>IH</sub>		$V_{CC} = 5.25 V,$	V <sub>I</sub> = 2.7 V				25			25	μA
I <sub>IL</sub>		V <sub>CC</sub> = 5.25 V,	V <sub>I</sub> = 0.4 V				-0.25			-0.25	mA
I <sub>OS</sub> ‡		V <sub>CC</sub> = 5.25 V,	V <sub>O</sub> = 0.5 V		-30		-90	-30		-90	mA
I <sub>CC</sub>		V <sub>CC</sub> = 5.25 V,	V <sub>I</sub> = GND,	Outputs open		120	180		120	180	mA

#### switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

DADAMETE	FROM	то	TEST CONDITIONS	TIB	PAL22V1	0C	TIBP	DAC	UNIT	
PARAMETE	n (INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT
f <sub>max</sub> ¶	With fe	With feedback		18			28.5			MHz
t <sub>pd</sub>	I, I/O	I/O	R1 = 300 Ω,		15	35		15	25	ns
t <sub>pd</sub>	I, I/O (reset)	Q	R2 = 390 Ω,		15	40		15	30	ns
t <sub>pd</sub>	CLK	Q	See Figure 4		10	25		10	15	ns
t <sub>en</sub>	I, I/O	I/O, Q			15	35		15	25	ns
t <sub>dis</sub>	I, I/O	I/O, Q			15	35		15	25	ns

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . <sup>‡</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.  $V_O$  is set at 0.5 V to avoid test problems caused by test equipment ground degradation.



#### TIBPAL22V10AM is Not Recommended For New Designs

## TIBPAL22V10AM HIGH-PERFORMANCE IMPACT ™ PROGRAMMABLE ARRAY LOGIC CIRCUITS

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage (see Note 1)	–5.5 V
Voltage range applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	–55°C to 125°C
Storage temperature range	–65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

#### recommended operating conditions

			MIN	NOM	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	V		
V <sub>IH</sub>	High-level input voltage	2		5.5	V		
VIL	Low-level input voltage			0.8	V		
I <sub>OH</sub>	High-level output current				-2	mA	
I <sub>OL</sub>	Low-level output current			12	mA		
f <sub>clock</sub>	Clock frequency <sup>†</sup>			22	MHz		
+	Pulse duration	Clock high or low	20			ns	
t <sub>w</sub>		Asynchronous reset high or low	30			115	
		Input	25				
+	Setup time before clock↑	Feedback	Feedback 25				
t <sub>su</sub>		Synchronous set	25			ns	
		Asynchronous reset low (inactive)	30				
t <sub>h</sub>	Hold time, input, set, or feedback after clock $\uparrow$	0			ns		
T <sub>A</sub>	Operating free-air temperature		-55		125	°C	

<sup>†</sup>  $f_{clock}$  (with feedback) =  $\frac{1}{t_{su} + t_{pd}(CLK \text{ to } Q)}$ ,  $f_{clock}$  (without feedback) =  $\frac{1}{t_{w}(low) + t_{w}(high)}$ 



## TIBPAL22V10AM HIGH-PERFORMANCE IMPACT ™ PROGRAMMABLE ARRAY LOGIC CIRCUITS

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#### electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIO	ONS	MIN	TYP <sup>†</sup>	MAX	UNIT
V <sub>IK</sub>	$V_{CC} = 4.5 V,$	l <sub>l</sub> = – 18 mA				-1.2	V
V <sub>OH</sub>	$V_{CC} = 4.5 V,$	I <sub>OH</sub> = -2 mA		2.4	3.5		V
V <sub>OL</sub>	$V_{CC} = 4.5 V,$	I <sub>OL</sub> = 12 mA			0.25	0.5	V
I <sub>OZH</sub>	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.7 V				0.1	mA
I <sub>OZL</sub>	$V_{CC} = 5.5 V,$	$V_{O} = 0.4 V$				-100	μA
lı	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 5.5 V				1	mA
I <sub>IH</sub>	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V				25	μA
IIL	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 0.4 V				-0.25	mA
I <sub>OS</sub> ‡	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 0.5 V		-30		-90	mA
Icc	$V_{CC} = 5.5 V,$	V <sub>I</sub> = GND,	Outputs open		120	180	mA

#### switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP†	МАХ	UNIT
f <sub>max</sub> ¶	With fee	edback		22			MHz
t <sub>pd</sub>	I, I/O	I/O	R1 = 390 Ω,		15	30	ns
t <sub>pd</sub>	I, I/O (reset)	Q	R2 = 750 Ω,		15	35	ns
t <sub>pd</sub>	CLK	Q	See Figure 4		10	20	ns
t <sub>en</sub>	I, I/O	I/O, Q			15	30	ns
t <sub>dis</sub>	I, I/O	I/O, Q			15	30	ns

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . <sup>‡</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.  $V_O$  is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

 $\label{eq:max} \mbox{(with feedback)} = \frac{1}{t_{SU} + t_{pd}(CLK \mbox{ to } Q)}, \mbox{ fmax (without feedback)} = \frac{1}{t_{W}(low) + t_{W}(high)}$ 

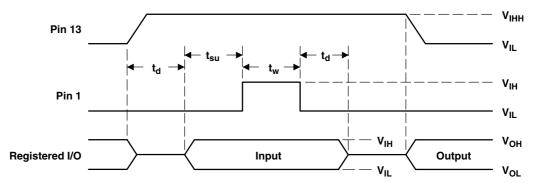


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#### preload procedure for registered outputs (see Notes 2 and 3)

The output registers can be preloaded to any desired state during device testing. This permits any state to be tested without having to step through the entire state-machine sequence. Each register is preloaded individually by following the steps given below:

- Step 1. With  $V_{CC}$  at 5 V and pin 1 at  $V_{IL}$ , raise pin 13 to  $V_{IHH}$ .
- Step 2. Apply either V<sub>IL</sub> or V<sub>IH</sub> to the output corresponding to the register to be preloaded.
- Step 3. Pulse pin 1, clocking in preload data.
- Step 4. Remove output voltage, then lower pin 13 to V<sub>IL</sub>. Preload can be verified by observing the voltage level at the output pin.



#### Figure 2. Preload Waveforms

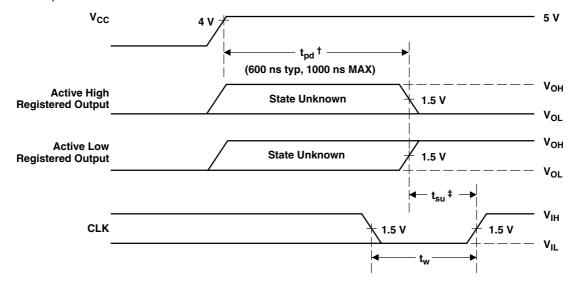
- NOTES: 2. Pin numbers shown are for JT and NT packages only. If chip-carrier socket adapter is not used, pin numbers must be changed accordingly.
  - 3.  $t_d$  =  $t_{su}$  =  $t_w$  = 100 ns to 1000 ns.  $V_{IHH}$  = 10.25 V to 10.75 V.



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#### power-up reset

Following power up, all registers are reset to zero. The output level depends on the polarity selected during programming. This feature provides extra flexibility to the system designer and is especially valuable in simplifying state-machine initialization. To ensure a valid power-up reset, it is important that the rise of  $V_{CC}$  be monotonic. Following power-up reset, a low-to-high clock transition must not occur until all applicable input and feedback setup times are met.



<sup>†</sup> This is the power-up reset time and applies to registered outputs only. The values shown are from characterization data. <sup>‡</sup> This is the setup time for input or feedback.

#### Figure 3. Power-Up Reset Waveforms

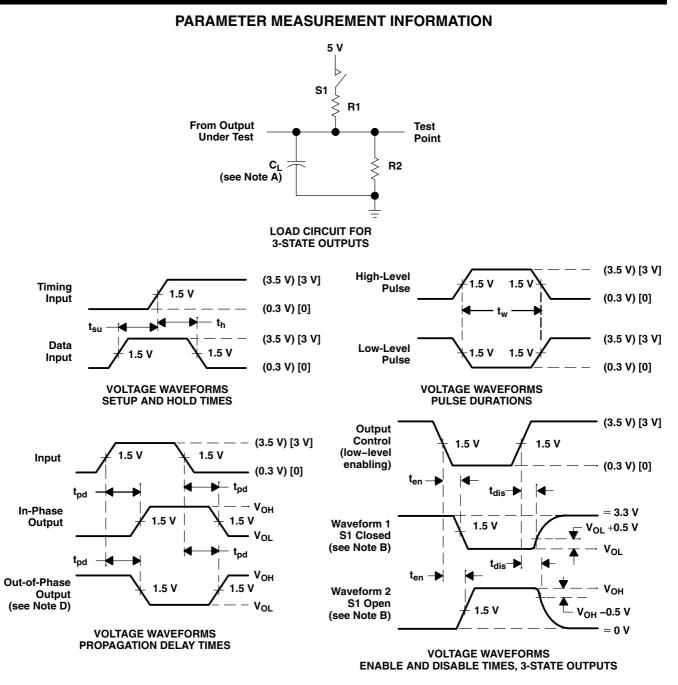
#### programming information

Texas Instruments programmable logic devices can be programmed using widely available software and inexpensive device programmers.

Complete programming specifications, algorithms, and the latest information on hardware, software, and firmware are available upon request. Information on programmers capable of programming Texas Instruments programmable logic is also available, upon request, from the nearest TI field sales office, local authorized TI distributor, or by calling Texas Instruments at (214) 997-5666.



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- NOTES: A. C<sub>L</sub> includes probe and jig capacitance and is 50 pF for  $t_{pd}$  and  $t_{en}$ , 5 pF for  $t_{dis}$ .
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses have the following characteristics: For C suffix, use the voltage levels indicated in parentheses (). PRR  $\leq$  1 MHz, t<sub>r</sub> = t<sub>f</sub>  $\leq$  2 ns, duty cycle = 50%. For M suffix, use the voltage levels indicated in brackets []. PRR  $\leq$  10 MHz, t<sub>r</sub> and t<sub>f</sub>  $\leq$  2 ns, duty cycle = 50%.
  - D. When measuring propagation delay times of 3-state outputs, switch S1 is closed.
  - E. Equivalent loads may be used for testing.

#### Figure 4. Load Circuit and Voltage Waveforms





25-Jan-2018

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86053013A	LIFEBUY	LCCC	FK	28	1	TBD	Call TI	Call TI	-55 to 125	5962- 86053013A TIBPAL22 V10AMFKB	
5962-8605301KA	LIFEBUY	CFP	W	24	1	TBD	Call TI	Call TI	-55 to 125	5962-8605301KA TIBPAL22V10AMW B	
TIBPAL22V10AMFKB	LIFEBUY	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86053013A TIBPAL22 V10AMFKB	
TIBPAL22V10AMJT	LIFEBUY	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	TIBPAL22V10AMJ T	
TIBPAL22V10AMWB	LIFEBUY	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8605301KA TIBPAL22V10AMW B	

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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## PACKAGE OPTION ADDENDUM

25-Jan-2018

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## **MECHANICAL DATA**

MCER004A - JANUARY 1995 - REVISED JANUARY 1997

## JT (R-GDIP-T\*\*)

#### **CERAMIC DUAL-IN-LINE**

24 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

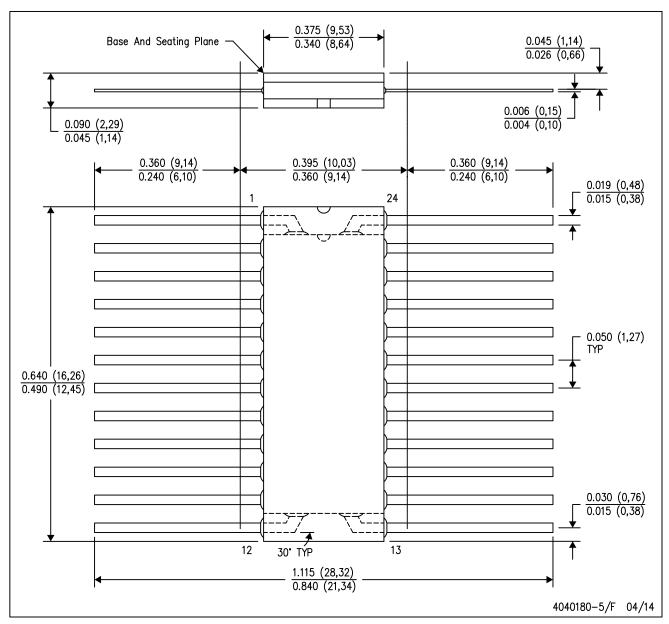
B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



CERAMIC DUAL FLATPACK

W (R-GDFP-F24)



NOTES: A. All linear dimensions are in inches (millimeters).

- This drawing is subject to change without notice. В.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
  E. Falls within Mil-Std 1835 GDFP2-F20



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